

06-04-2002



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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

6-4-02

1. Name of conveying party(ies):  
a) Sampo Semiconductor Corporation  
b) 6-4-02  
c)  
d)  
Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies):  
Name: Amkor Technology, Inc.  
Internal Address:  
Street Address: 1900 South Price Road  
City: Chandler State: AZ Zip: 85248-1604  
Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other  
Execution Date: May 2, 2002

4. Application number(s) or patent number(s):  
If this document is being filed with a new application, the execution date of the application is:  
A. Patent Application No.(s)  
B. Patent No.(s)  
6,201,302, issued March 13, 2001  
Additional numbers attached?  Yes  No

6. Total no. of applications and patents involved: 1  
7. Total fee (37 CFR 3.41) ..... \$40.00  
 Enclosed  
 Authorized to charge any additional fees to deposit account  
8. Deposit account number:  
50-0553  
(Attach duplicate copy of this page if paying by deposit account)

5. Name and address of party to whom correspondence concerning document should be mailed:  
Name: Serge J. Hodgson  
Gunnison, McKay & Hodgson, L.L.P.  
Internal Address:  
Street Address: Garden West Office Plaza  
Suite 220  
1900 Garden Road  
City: Monterey State: CA Zip: 93940

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9. Statement and signature.  
*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*  
Serge J. Hodgson June 3, 2002  
Name of Person Signing Signature Date  
Total number of pages including cover sheet, attachments, and documents: 2

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231

06/04/2002 6TDM11 00000240 6201302  
01 FC:581 40.00 OP

# Patent Assignment

For good and valuable consideration, receipt of which is hereby acknowledged, Sampo Semiconductor Corporation ("Sampo") having a place of business at, No. 1 Chung Feng Road, Kao Ping Section, Lung Tan, Taoyuan County, Taiwan, Republic of China does hereby sell, assign and transfer to Amkor Technology, Inc., a Delaware corporation, having a place of business at 1900 S. Price Road, Chandler, AZ 85248-1604, its successors and assigns, the entire right, title and interest throughout the world in U.S. Patent 6,201,302, entitled Semiconductor Package Having Multi-Dies, issued March 13, 2001, including divisions, reissues, continuations and extensions thereof.

In witness thereof, this Patent Assignment is executed, on this 2<sup>nd</sup> day of May, 2002.



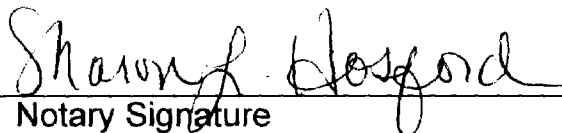
Eric Larson, Chairman  
Sampo Semiconductor Corporation

State of Arizona

SS

County of Maricopa

On this date 2<sup>nd</sup> of May, 2002, before me, Sharon L. Hosford, personally appeared Eric Larson, whose identity was proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to this document, and who acknowledged that he/she signed the above/attached document.



Notary Signature

My Commission Expires: March 31, 2004

